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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Yeo et al.

Serial No. 10/078,718

Filed February 19, 2002

For: **Enhanced Chip Scale Package For
Wire Bond Dies**

Attorney's Docket No. 4795-002

Examiner
Group Art Unit 2833

Raleigh, North Carolina

May 1, 2002

Commissioner for Patents
Washington, D.C. 20231

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Dear Sir:

The above-identified application claims priority based on Singapore Application No. 200106786-7. Enclosed please find a certified copy of Singapore Application No. 200106786-7. We filed the above-identified U.S. application without the certified copy.

Respectfully submitted,

By:

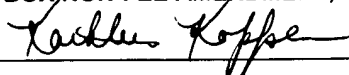
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